

RF Power Field Effect Transistor

N-Channel Enhancement-Mode Lateral MOSFET

Designed for broadband commercial and industrial applications with frequencies up to 1000 MHz. The high gain and broadband performance of this device make it ideal for large-signal, common-source amplifier applications in 26 volt base station equipment.

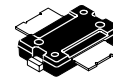
- Typical Single-Carrier N-CDMA Performance @ 880 MHz, $V_{DD} = 26$ Volts, $I_{DQ} = 600$ mA, $P_{out} = 14$ Watts Avg., IS-95 CDMA (Pilot, Sync, Paging, Traffic Codes 8 Through 13)
Power Gain — 17.8 dB
Drain Efficiency — 30%
ACPR @ 750 kHz Offset — -47 dBc in 30 kHz Bandwidth
- Capable of Handling 10:1 VSWR, @ 26 Vdc, 880 MHz, 70 Watts CW Output Power

Features

- Characterized with Series Equivalent Large-Signal Impedance Parameters
- Integrated ESD Protection
- 200°C Capable Plastic Package
- N Suffix Indicates Lead-Free Terminations. RoHS Compliant.
- In Tape and Reel. R1 Suffix = 500 Units per 24 mm, 13 inch Reel.

MRF5S9070NR1

**880 MHz, 70 W, 26 V
SINGLE N-CDMA
LATERAL N-CHANNEL
BROADBAND
RF POWER MOSFET**



**CASE 1265-08, STYLE 1
TO-270-2
PLASTIC**

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	- 0.5, +68	Vdc
Gate-Source Voltage	V_{GS}	- 0.5, +15	Vdc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	219 1.25	W W/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 65 to +150	$^\circ\text{C}$
Operating Junction Temperature	T_J	200	$^\circ\text{C}$

Table 2. Thermal Characteristics

Characteristic	Symbol	Value ^(1,2)	Unit
Thermal Resistance, Junction to Case Case Temperature 80°C , 70 W CW Case Temperature 78°C , 14 W CW	$R_{\theta JC}$	0.80 0.93	$^\circ\text{C/W}$

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22-A114)	2 (Minimum)
Machine Model (per EIA/JESD22-A115)	A (Minimum)
Charge Device Model (per JESD22-C101)	IV (Minimum)

Table 4. Moisture Sensitivity Level

Test Methodology	Rating	Package Peak Temperature	Unit
Per JESD 22-A113, IPC/JEDEC J-STD-020	1	260	$^\circ\text{C}$

1. MTTF calculator available at <http://www.freescale.com/rf>. Select Tools/Software/Application Software/Calculators to access the MTTF calculators by product.
2. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1955.

Table 5. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Off Characteristics					
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 68\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 26\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	1	μAdc
On Characteristics					
Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 200\text{ }\mu\text{A}$)	$V_{GS(th)}$	2	2.7	4	Vdc
Gate Quiescent Voltage ($V_{DS} = 26\text{ Vdc}$, $I_D = 600\text{ mAdc}$)	$V_{GS(Q)}$	—	3.7	—	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 1.0\text{ Adc}$)	$V_{DS(on)}$	—	0.18	0.22	Vdc
Forward Transconductance ($V_{DS} = 10\text{ Vdc}$, $I_D = 4\text{ Adc}$)	g_{fs}	—	4.7	—	S
Dynamic Characteristic					
Input Capacitance ($V_{DS} = 26\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{iss}	—	126	—	pF
Output Capacitance ($V_{DS} = 26\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{oss}	—	34	—	pF
Reverse Transfer Capacitance ($V_{DS} = 26\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{rss}	—	1.37	—	pF
Functional Tests (In Freescale Test Fixture, 50 ohm system) $V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 600\text{ mA}$, $P_{out} = 14\text{ W Avg.}$, $f = 880\text{ MHz}$, Single-Carrier N-CDMA, 1.2288 MHz Channel Bandwidth Carrier. ACPR measured in 30 kHz Channel Bandwidth @ $\pm 750\text{ kHz}$ Offset. PAR = 9.8 dB @ 0.01% Probability on CCDF					
Power Gain	G_{ps}	17	17.8	—	dB
Drain Efficiency	η_D	29	30	—	%
Adjacent Channel Power Ratio	ACPR	—	-47	-45	dBc
Input Return Loss	IRL	—	-19	-9	dB
Typical GSM CW Performances (In Freescale GSM Test Fixture Optimized for 921-960 MHz, 50 ohm system) $V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 400\text{ mA}$, $P_{out} = 60\text{ W}$, $f = 921\text{ - }960\text{ MHz}$					
Power Gain	G_{ps}	—	16.4	—	dB
Drain Efficiency	η_D	—	62	—	%
Input Return Loss	IRL	—	-12	—	dB
P_{out} @ 1 dB Compression Point ($f = 940\text{ MHz}$)	P1dB	—	68	—	W
Typical GSM EDGE Performances (In Freescale GSM EDGE Test Fixture Optimized for 921-960 MHz, 50 ohm system) $V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 400\text{ mA}$, $P_{out} = 25\text{ W Avg.}$, $f = 921\text{ - }960\text{ MHz}$, GSM EDGE Signal					
Power Gain	G_{ps}	—	17	—	dB
Drain Efficiency	η_D	—	44	—	%
Error Vector Magnitude	EVM	—	1.5	—	%
Spectral Regrowth at 400 kHz Offset	SR1	—	-62	—	dBc
Spectral Regrowth at 600 kHz Offset	SR2	—	-78	—	dBc

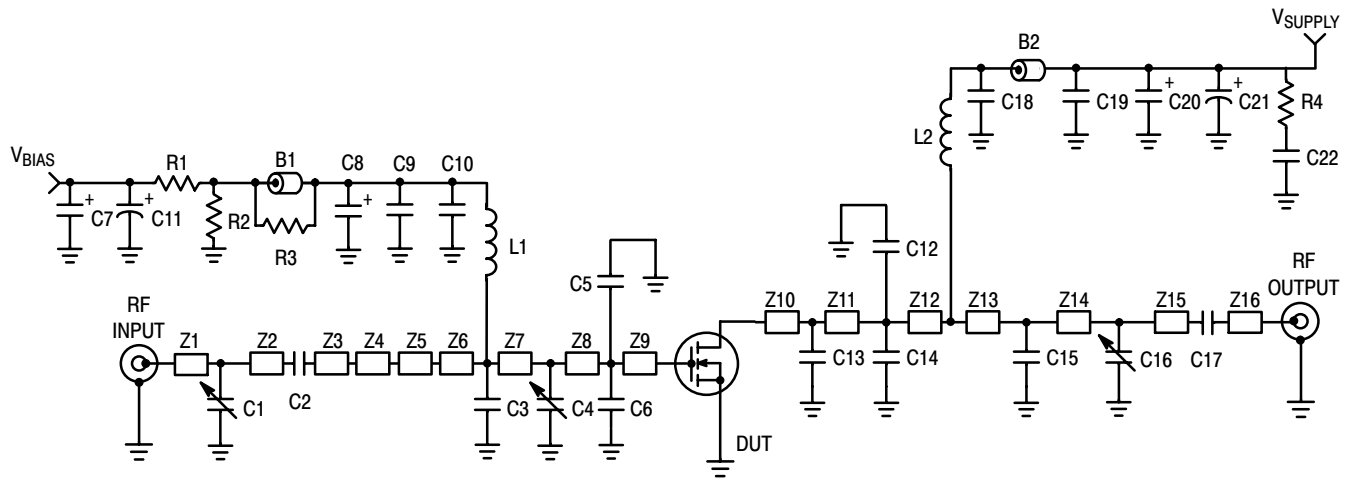
(continued)

Table 5. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted) (continued)

Characteristic	Symbol	Min	Typ	Max	Unit
Typical GSM CW Performances (In Freescale GSM Test Fixture Optimized for 865-895 MHz, 50 ohm system) $V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 400\text{ mA}$, $P_{out} = 60\text{ W}$, $f = 865\text{--}895\text{ MHz}$					
Power Gain	G_{ps}	—	16.4	—	dB
Drain Efficiency	η_D	—	59	—	%
Input Return Loss	IRL	—	-15	—	dB
P_{out} @ 1 dB Compression Point ($f = 880\text{ MHz}$)	P1dB	—	71	—	W

Typical GSM EDGE Performances (In Freescale GSM EDGE Test Fixture Optimized for 865-895 MHz, 50 ohm system)
 $V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 400\text{ mA}$, $P_{out} = 25\text{ W Avg.}$, $f = 865\text{--}895\text{ MHz}$, GSM EDGE Signal

Power Gain	G_{ps}	—	17	—	dB
Drain Efficiency	η_D	—	41	—	%
Error Vector Magnitude	EVM	—	1.35	—	%
Spectral Regrowth at 400 kHz Offset	SR1	—	-66	—	dBc
Spectral Regrowth at 600 kHz Offset	SR2	—	-81	—	dBc

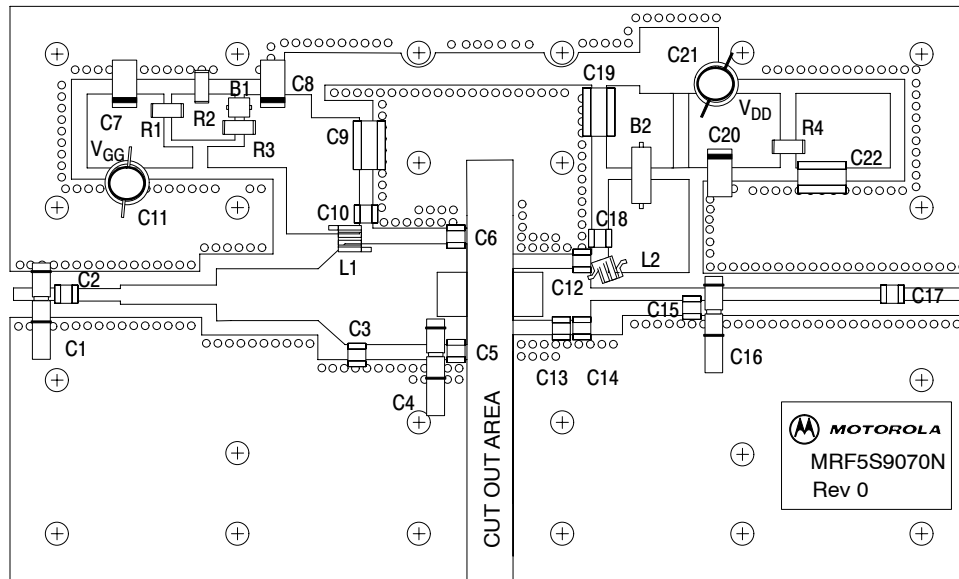


Z1	0.140" x 0.060" Microstrip	Z10	0.245" x 0.270" Microstrip
Z2	0.141" x 0.060" Microstrip	Z11	0.110" x 0.270" Microstrip
Z3	0.280" x 0.060" Microstrip	Z12	0.055" x 0.270" Microstrip
Z4	0.500" x 0.100" Microstrip	Z13	0.512" x 0.060" Microstrip
Z5	0.530" x 0.270" Microstrip	Z14	0.106" x 0.060" Microstrip
Z6	0.155" x 0.270" x 0.530" Taper	Z15	0.930" x 0.060" Microstrip
Z7	0.376" x 0.530" Microstrip	Z16	0.365" x 0.060" Microstrip
Z8	0.116" x 0.530" Microstrip	PCB	Taconic RF-35, 0.030", $\epsilon_r = 3.5$
Z9	0.055" x 0.530" Microstrip		

Figure 1. MRF5S9070NR1 Test Circuit Schematic

Table 6. MRF5S9070NR1 Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
B1	Small Ferrite Bead, Surface Mount	2743019447	Fair-Rite
B2	Large Ferrite Bead, Surface Mount	2743021447	Fair-Rite
C1	0.6 - 6.0 pF Variable Capacitor, Gigatrim	272715L	Johanson
C2	16 pF Chip Capacitor	100B160JP500X	ATC
C3	7.5 pF Chip Capacitor	100B7R5JP500X	ATC
C4, C16	0.8 - 8.0 pF Variable Capacitor, Gigatrim	272915L	Johanson
C5, C6	15 pF Chip Capacitors	100B150JP500X	ATC
C7, C8, C20	10 μ F, 35 V Tantalum Capacitors	T491D106K035AS	Kemet
C9, C19, C22	0.58 μ F Chip Capacitors	700A561MP150X	ATC
C10, C18	18 pF Chip Capacitors	100B180JP500X	ATC
C11	100 μ F, 50 V Electrolytic Capacitor	515D107M050BB6A	Vishay-Dale
C12, C14	13 pF Chip Capacitors	100B130JP500X	ATC
C13	0.7 pF Chip Capacitor	100B0R7BP500X	ATC
C15	3.9 pF Chip Capacitor	100B3R9JP500X	ATC
C17	22 pF Chip Capacitor	100B180JP500X	ATC
C21	470 μ F, 63 V Electrolytic Capacitor	SME63VB471M12X25LL	United Chemi-Con
L1, L2	12.5 nH Surface Mount Inductors	A04T-5	Coilcraft
R1	1 k Ω Chip Resistor		
R2	560 k Ω Chip Resistor		
R3	12 Ω Chip Resistor		
R4	27 Ω Chip Resistor		



Freescall has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescall Semiconductor signature/logo. PCBs may have either Motorola or Freescall markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 2. MRF5S9070NR1 Test Circuit Component Layout

TYPICAL CHARACTERISTICS

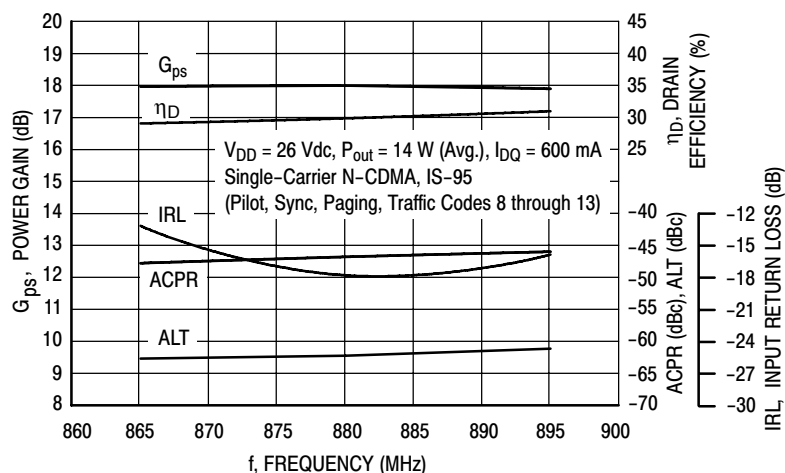


Figure 3. Class AB Broadband Performance

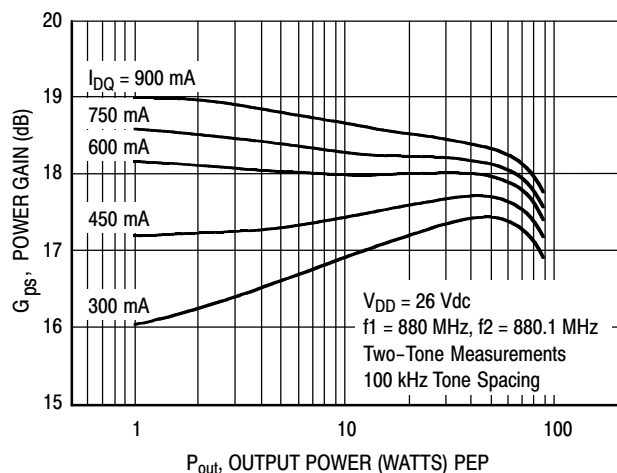


Figure 4. Two-Tone Power Gain versus Output Power

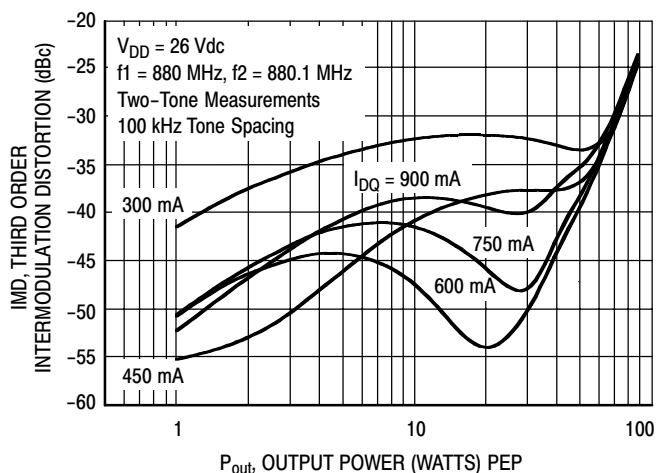


Figure 5. Third Order Intermodulation Distortion versus Output Power

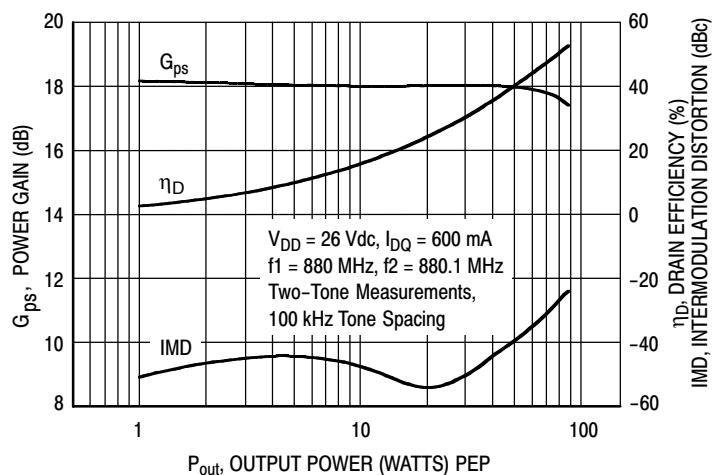


Figure 6. Power Gain, Drain Efficiency and IMD versus Output Power

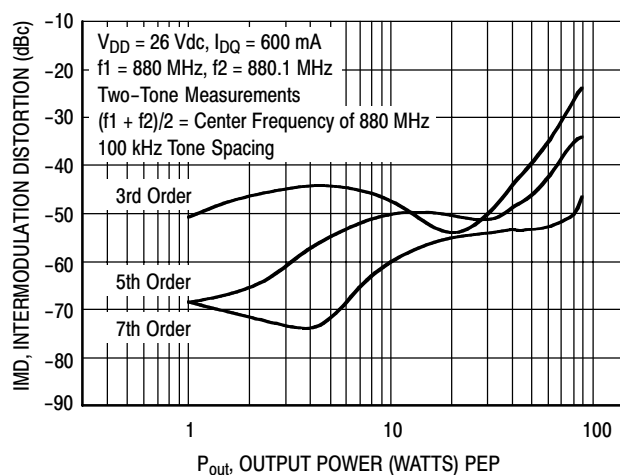


Figure 7. Intermodulation Distortion Products versus Output Power

TYPICAL CHARACTERISTICS

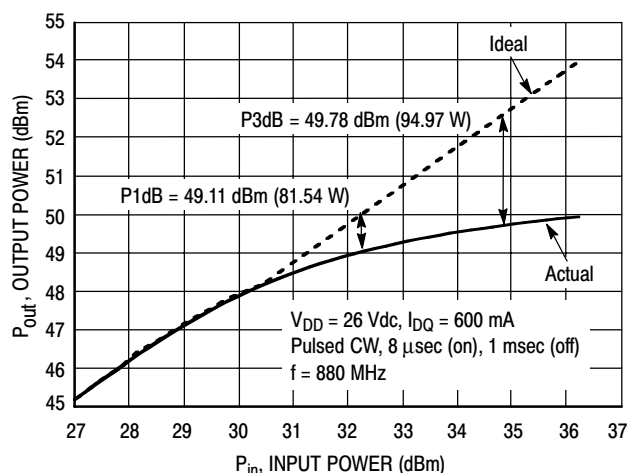


Figure 8. Pulse CW Output Power versus Input Power

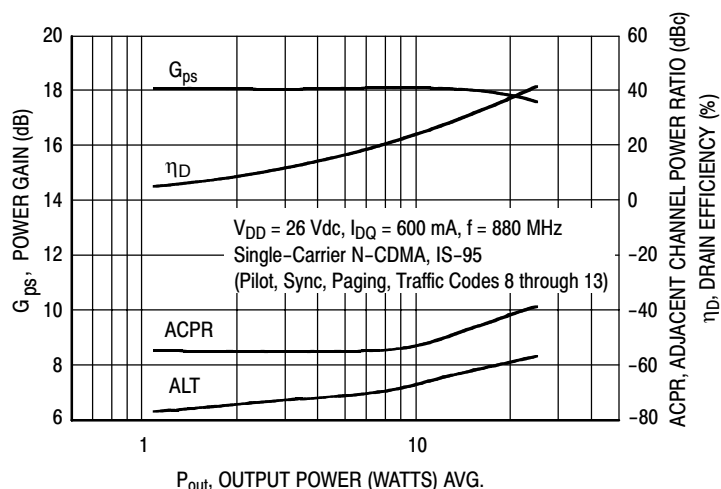


Figure 9. N-CDMA ACPR, Power Gain and Drain Efficiency versus Output Power

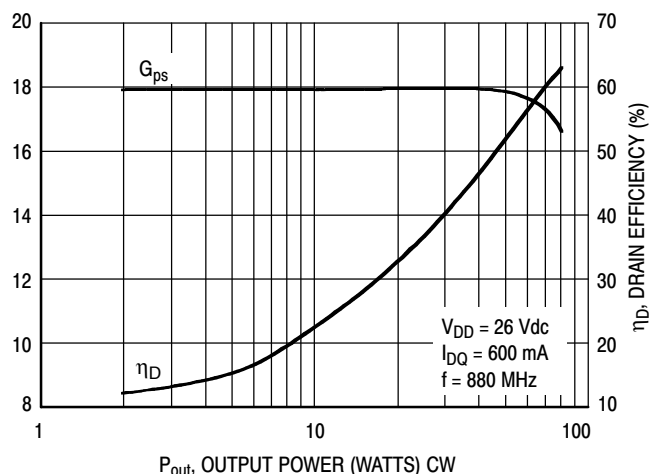
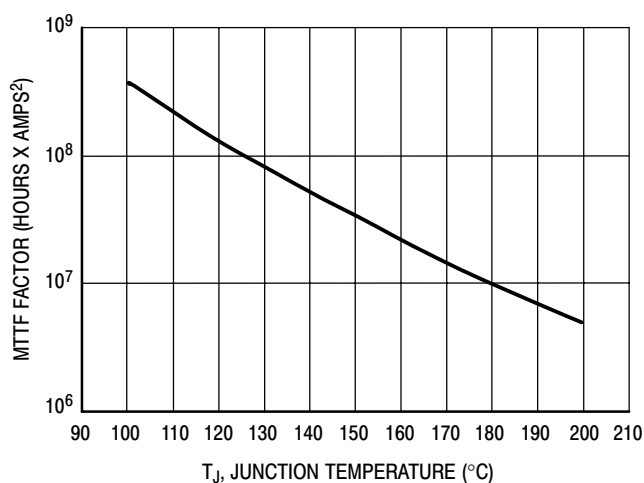


Figure 10. Power Gain and Drain Efficiency versus CW Output Power



This above graph displays calculated MTTF in hours x ampere² drain current. Life tests at elevated temperatures have correlated to better than $\pm 10\%$ of the theoretical prediction for metal failure. Divide MTTF factor by I_D^2 for MTTF in a particular application.

Figure 11. MTTF Factor versus Junction Temperature

N-CDMA TEST SIGNAL

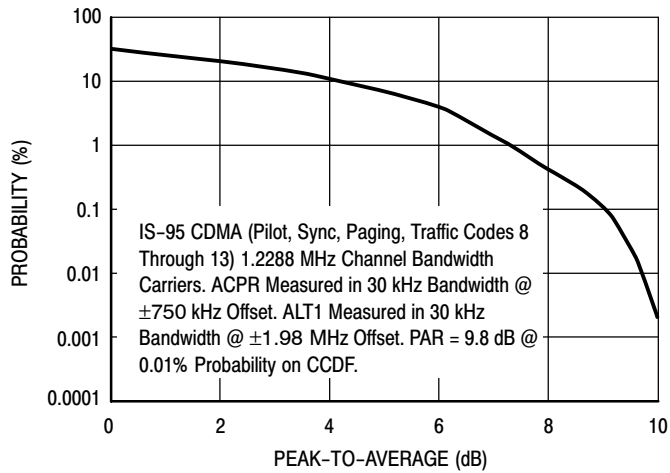


Figure 12. Single-Carrier CCDF N-CDMA

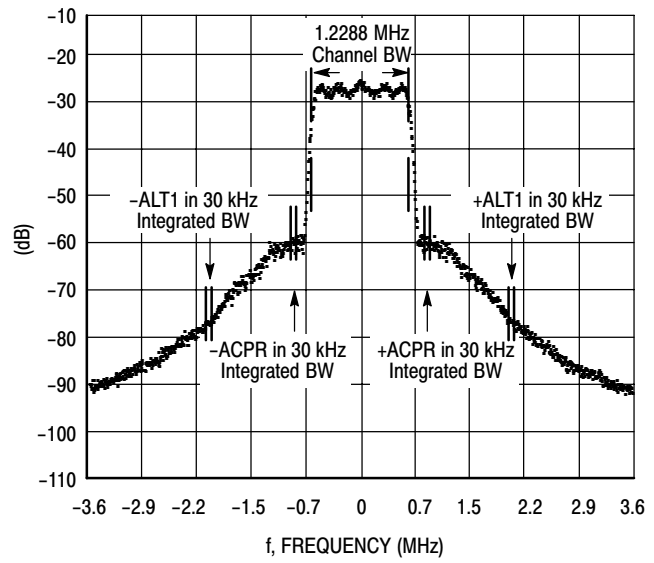
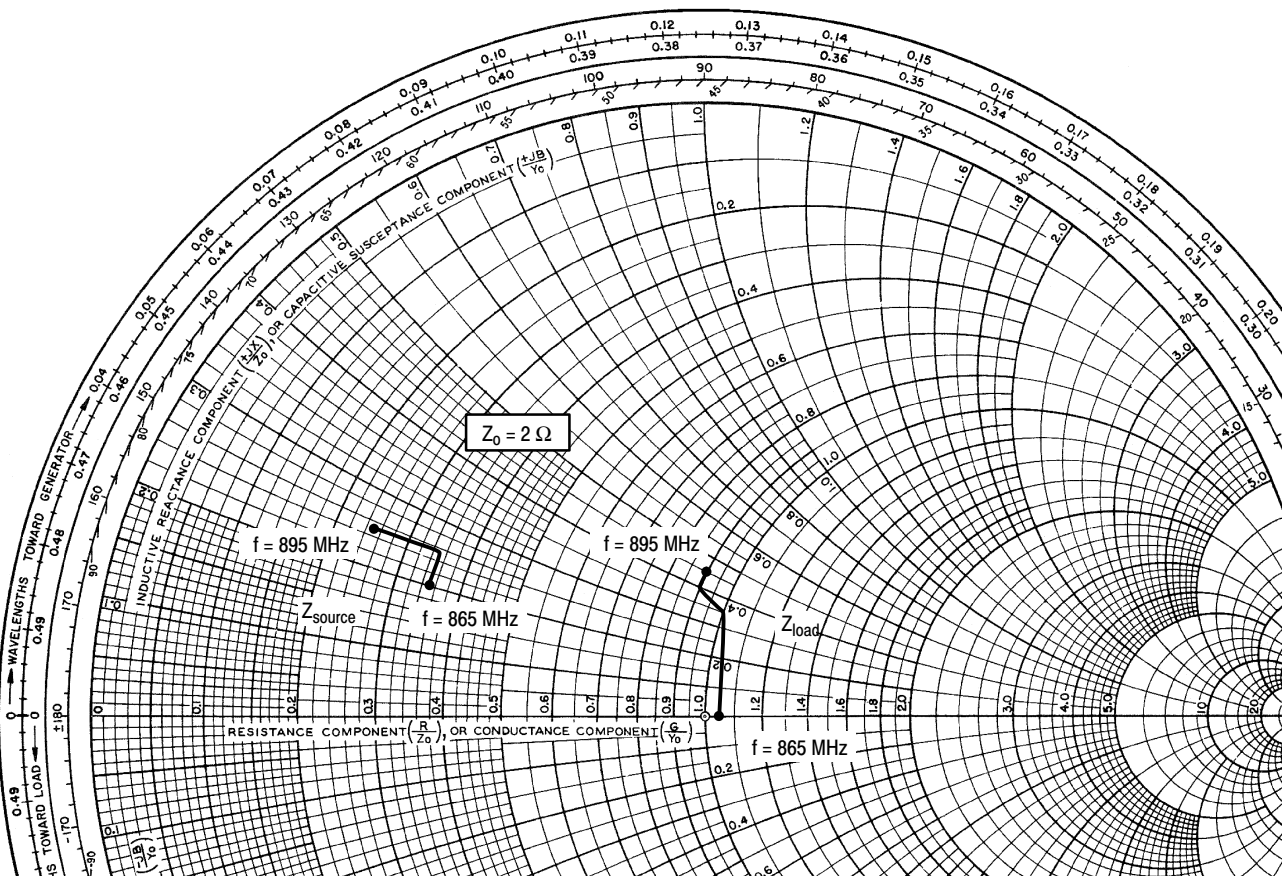


Figure 13. Single-Carrier N-CDMA Spectrum



$V_{DD} = 26 \text{ Vdc}$, $I_{DQ} = 600 \text{ mA}$, $P_{out} = 14 \text{ W Avg.}$

f MHz	Z_{source} Ω	Z_{load} Ω
865	$0.7 + j0.4$	$2.1 + j0.6$
875	$0.7 + j0.5$	$2.0 + j0.7$
885	$0.6 + j0.5$	$1.8 + j0.8$
895	$0.5 + j0.5$	$1.8 + j0.9$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

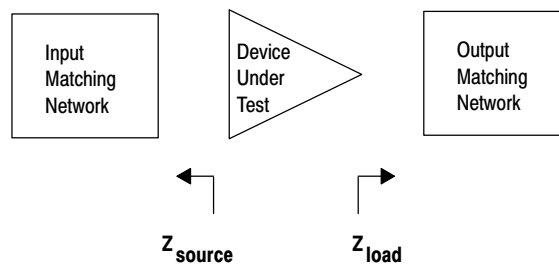


Figure 14. Series Equivalent Source and Load Impedance

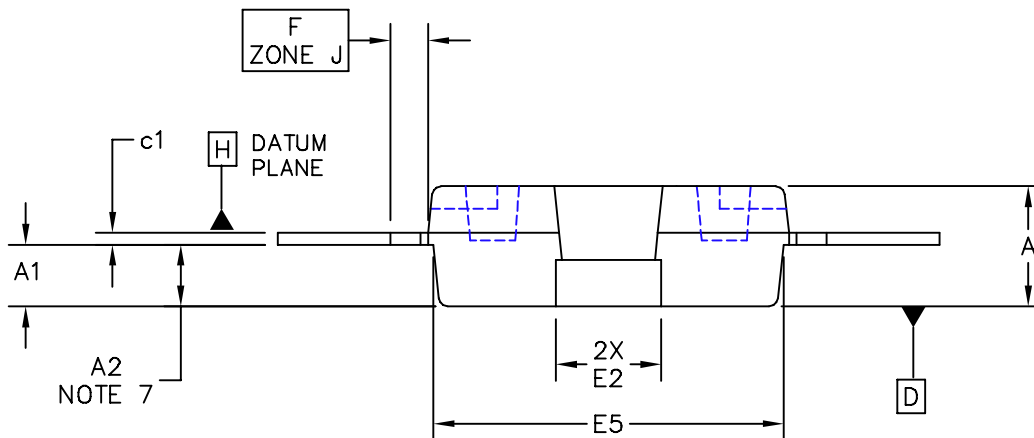
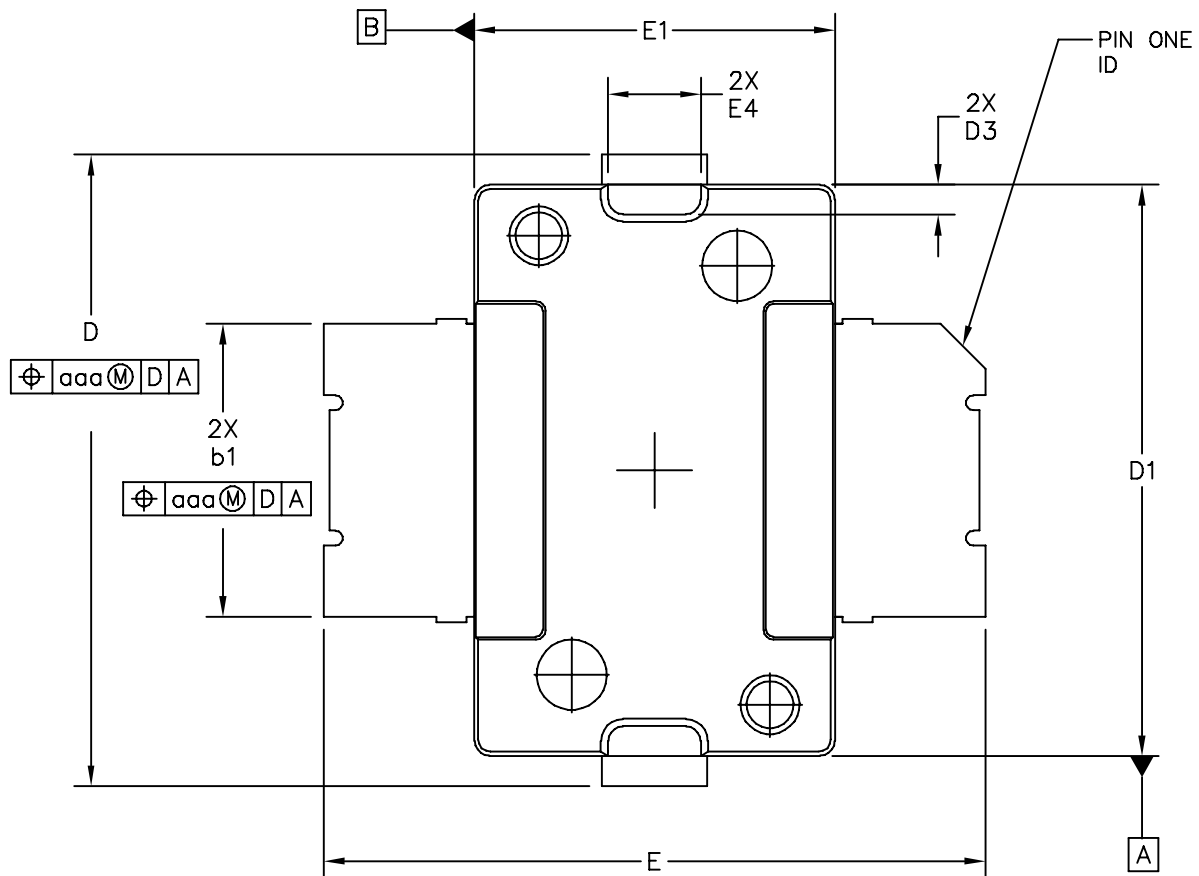


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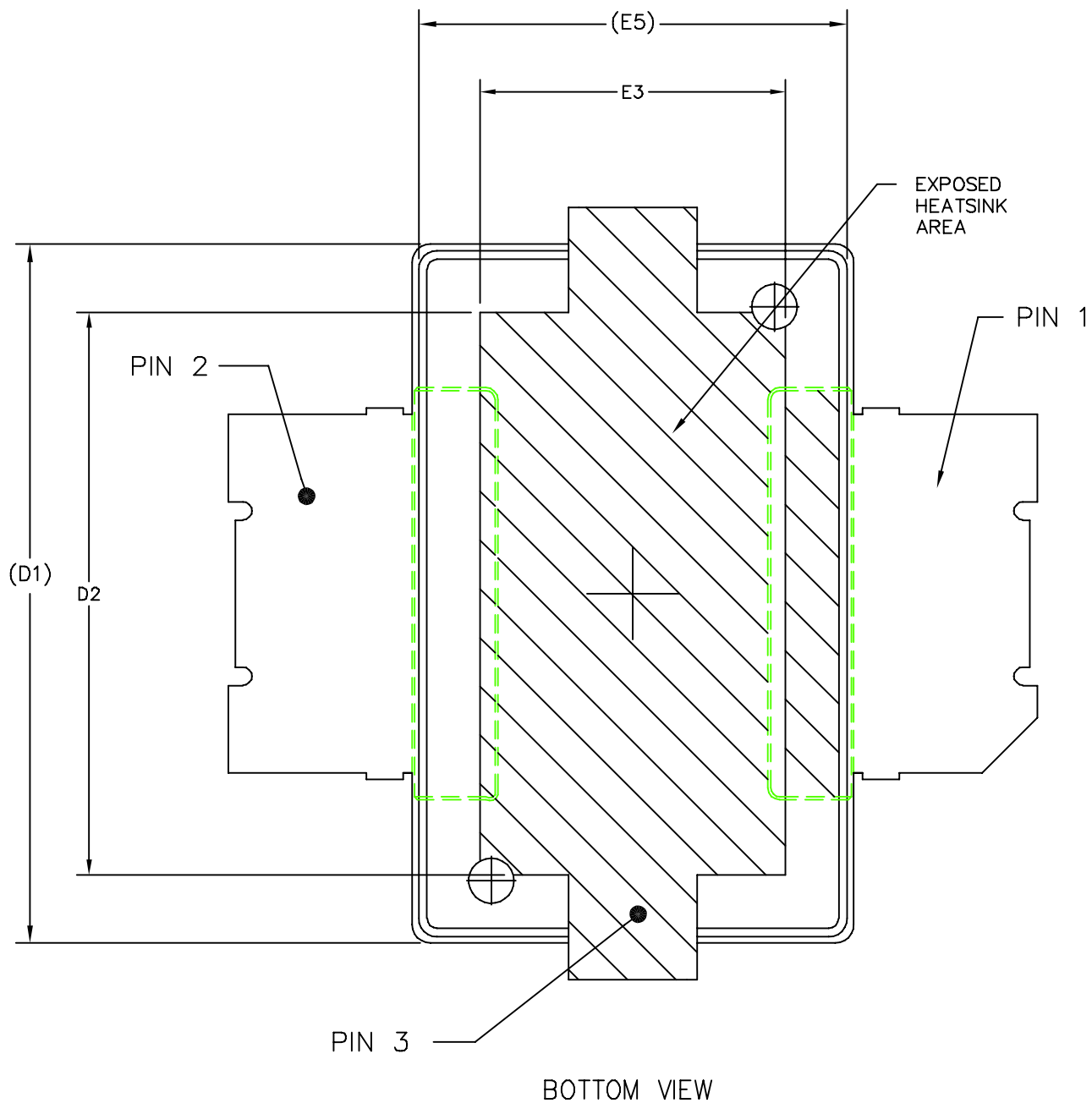
NOTES

PACKAGE DIMENSIONS



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TITLE: TO-270 SURFACE MOUNT			DOCUMENT NO: 98ASH98117A		REV: J
			CASE NUMBER: 1265-08		01 APR 2005
			STANDARD: NON-JEDEC		

MRF5S9070NR1



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		STANDARD: NON-JEDEC	

NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D1" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D1" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSION "b1" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE "b1" DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION "A2" APPLIES WITHIN ZONE "J" ONLY.
8. DIMENSIONS "D" AND "E2" DO NOT INCLUDE MOLD PROTRUSION. OVERALL LENGTH INCLUDING MOLD PROTRUSION SHOULD NOT EXCEED 0.430 INCH FOR DIMENSION "D" AND 0.080 INCH FOR DIMENSION "E2". DIMENSIONS "D" AND "E2" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -D-.

STYLE 1:

PIN 1 - DRAIN
PIN 2 - GATE
PIN 3 - SOURCE

INCH			MILLIMETER		INCH			MILLIMETER	
DIM	MIN	MAX	MIN	MAX	DIM	MIN	MAX	MIN	MAX
A	.078	.082	1.98	2.08	F	.025 BSC		0.64 BSC	
A1	.039	.043	0.99	1.09	b1	.193	.199	4.90	5.06
A2	.040	.042	1.02	1.07	c1	.007	.011	0.18	0.28
D	.416	.424	10.57	10.77	aaa	.004		0.10	
D1	.378	.382	9.60	9.70					
D2	.290	.320	7.37	8.13					
D3	.016	.024	0.41	0.61					
E	.436	.444	11.07	11.28					
E1	.238	.242	6.04	6.15					
E2	.066	.074	1.68	1.88					
E3	.150	.180	3.81	4.57					
E4	.058	.066	1.47	1.68					
E5	.231	.235	5.87	5.97					
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